

MOSFETs Silicon N-channel MOS (U-MOSIX-H)

# TK110P10PL

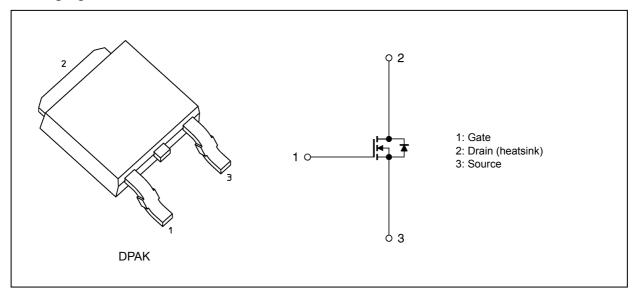
### 1. Applications

- · High-Efficiency DC-DC Converters
- · Switching Voltage Regulators
- · Motor Drivers

#### 2. Features

- (1) High-speed switching
- (2) Small gate charge:  $Q_{SW} = 9.3 \text{ nC (typ.)}$
- (3) Small output charge:  $Q_{oss} = 32 \text{ nC (typ.)}$
- (4) Low drain-source on-resistance:  $R_{DS(ON)} = 8.9 \text{ m}\Omega$  (typ.) ( $V_{GS} = 10 \text{ V}$ )
- (5) Low leakage current:  $I_{DSS}$  = 10  $\mu A$  (max) ( $V_{DS}$  = 100 V)
- (6) Enhancement mode:  $V_{th}$  = 1.5 to 2.5 V ( $V_{DS}$  = 10 V,  $I_D$  = 0.3 mA)

#### 3. Packaging and Internal Circuit





## 4. Absolute Maximum Ratings (Note) (Ta = 25 °C unless otherwise specified)

Characteris	Symbol	Rating	Unit		
Drain-source voltage			V <sub>DSS</sub>	100	V
Gate-source voltage			V <sub>GSS</sub>	±20	
Drain current (DC)	(T <sub>c</sub> = 25 °C)	(Note 1)	I <sub>D</sub>	40	Α
Drain current (DC)	(Silicon limit)	(Note 1), (Note 2)	I <sub>D</sub>	60	]
Drain current (pulsed)	(t = 100 μs)	(Note 1)	I <sub>DP</sub>	160	
Power dissipation	(T <sub>c</sub> = 25 °C)		$P_D$	75	W
Single-pulse avalanche energy		(Note 3)	E <sub>AS</sub>	18	mJ
Single-pulse avalanche current		(Note 3)	I <sub>AS</sub>	40	Α
Channel temperature			T <sub>ch</sub>	175	°C
Storage temperature			T <sub>stg</sub>	-55 to 175	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### 5. Thermal Characteristics

Characteristics		Symbol	Max	Unit
Channel-to-case thermal resistance	(T <sub>c</sub> = 25 °C)	R <sub>th(ch-c)</sub>	2.00	°C/W

Note 1: Ensure that the channel temperature does not exceed 175 °C.

Note 2: Limited by silicon chip capability.

Note 3:  $V_{DD}$  = 80 V,  $T_{ch}$  = 25 °C (initial), L = 8.7  $\mu H,\ I_{AS}$  = 40 A

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

#### 6. Electrical Characteristics

## 6.1. Static Characteristics (T<sub>a</sub> = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±0.1	μА
Drain cut-off current	I <sub>DSS</sub>	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V	_		10	
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	100	_	_	V
Drain-source breakdown voltage (Note 4)	V <sub>(BR)DSX</sub>	$I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$	65	_	_	
Gate threshold voltage	$V_{th}$	$V_{DS}$ = 10 V, $I_{D}$ = 0.3 mA	1.5	_	2.5	
Drain-source on-resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 16 A	_	11.5	16	mΩ
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A	_	8.9	10.6	

Note 4: If a reverse bias is applied between gate and source, this device enters  $V_{(BR)DSX}$  mode. Note that the drain-source breakdown voltage is lowered in this mode.



# 6.2. Dynamic Characteristics (T<sub>a</sub> = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 50 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	2040	_	pF
Reverse transfer capacitance	C <sub>rss</sub>		_	22	_	
Output capacitance	C <sub>oss</sub>		_	310	_	
Gate resistance	r <sub>g</sub>	_	_	1.6	_	Ω
Switching time (rise time)	t <sub>r</sub>	See Fig. 6.2.1	_	6	_	ns
Switching time (turn-on time)	t <sub>on</sub>		_	20	_	
Switching time (fall time)	t <sub>f</sub>		_	9	_	
Switching time (turn-off time)	t <sub>off</sub>		_	43	_	

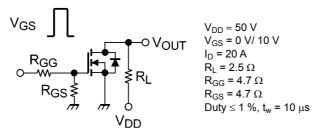


Fig. 6.2.1 Switching Time Test Circuit

# 6.3. Gate Charge Characteristics (T<sub>a</sub> = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus	Qg	$V_{DD} \approx 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$	_	33	_	nC
gate-drain)		$V_{DD} \approx 50 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 20 \text{ A}$		17		
Gate-source charge 1	Q <sub>gs1</sub>	$V_{DD} \approx 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$	_	6.7	_	
Gate-drain charge	$Q_{gd}$		_	6.7	_	
Gate switch charge	Q <sub>SW</sub>		_	9.3	_	
Output charge	Q <sub>oss</sub>	V <sub>DS</sub> = 50 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	32	_	

# 6.4. Source-Drain Characteristics ( $T_a = 25$ °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (pulsed) (Note	5) I <sub>DRP</sub>	(t = 100 μs)	_	_	160	Α
Diode forward voltage	V <sub>DSF</sub>	I <sub>DR</sub> = 40 A, V <sub>GS</sub> = 0 V	_	_	-1.5	V
Reverse recovery time	t <sub>rr</sub>	$I_{DR} = 10 \text{ A}, V_{GS} = 0 \text{ V},$	_	45	_	ns
Reverse recovery charge	Q <sub>rr</sub>	-dl <sub>DR</sub> /dt = 100 A/μs	_	63		nC

Note 5: Ensure that the channel temperature does not exceed 175 °C.

#### 7. Marking

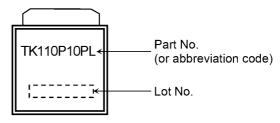


Fig. 7.1 Marking



### 8. Characteristics Curves (Note)

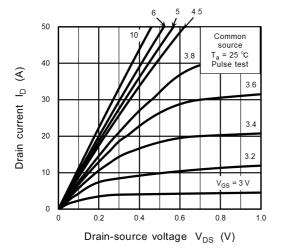


Fig. 8.1 I<sub>D</sub> - V<sub>DS</sub>

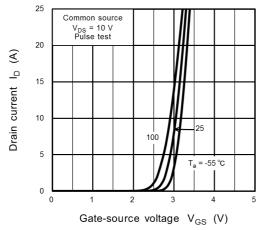


Fig. 8.3 I<sub>D</sub> - V<sub>GS</sub>

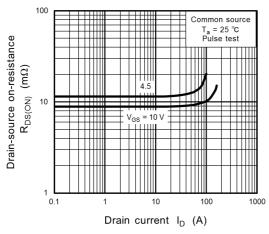


Fig. 8.5 R<sub>DS(ON)</sub> - I<sub>D</sub>

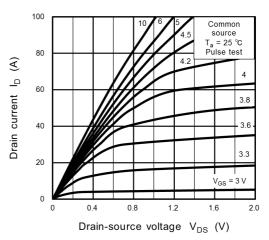


Fig. 8.2 I<sub>D</sub> - V<sub>DS</sub>

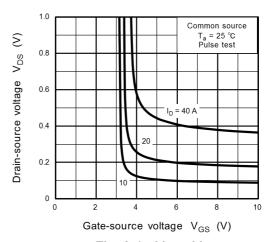


Fig. 8.4 VDS - VGS

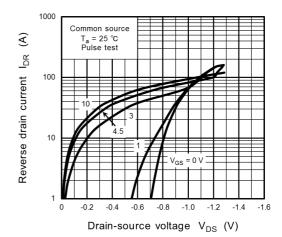


Fig. 8.6 IDR - VDS



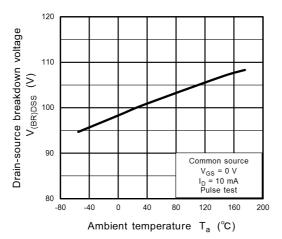


Fig. 8.7 V<sub>(BR)DSS</sub> - T<sub>a</sub>

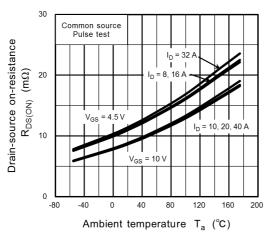


Fig. 8.9 RDS(ON) - Ta

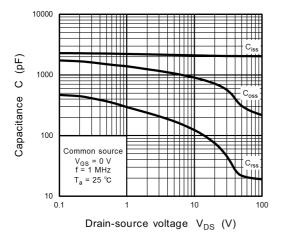


Fig. 8.11 Capacitance - V<sub>DS</sub>

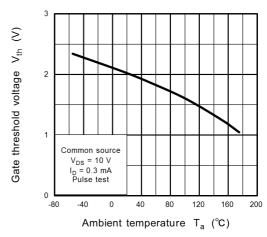


Fig. 8.8 V<sub>th</sub> - T<sub>a</sub>

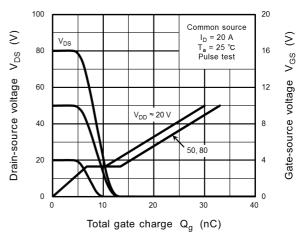


Fig. 8.10 Dynamic Input/Output Characteristics

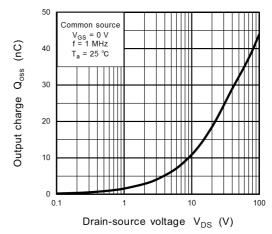


Fig. 8.12 Qoss - VDS



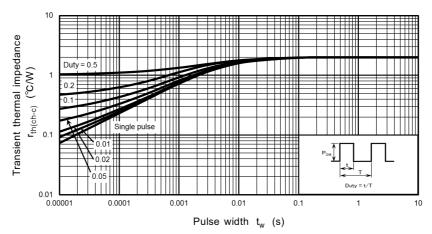


Fig. 8.13  $r_{th}$  -  $t_w$  (Guaranteed Maximum)

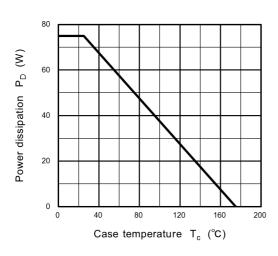


Fig. 8.14 P<sub>D</sub> - T<sub>c</sub> (Guaranteed Maximum)

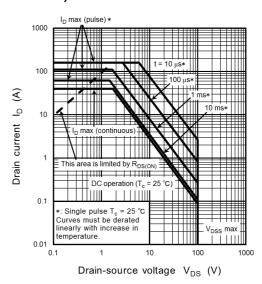


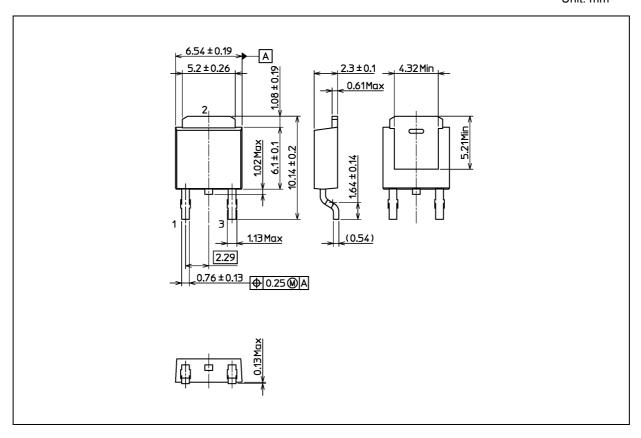
Fig. 8.15 Safe Operating Area (Guaranteed Maximum)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



# **Package Dimensions**

Unit: mm



Weight: 0.33 g (typ.)

	Package Name(s)
TOSHIBA: 2-7N1S	
Nickname: DPAK	



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